

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3258891

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HIROSHI TAMAGAWA	02/24/2015
YASUHIRO KONDO	02/24/2015
HIROKI YAMAMOTO	02/24/2015
RECEIVING PARTY DATA	
Name:	ROHM CO., LTD.
Street Address:	21, SAIIN MIZOSAKI-CHO, UKYO-KU, KYOTO-SHI
City:	KYOTO
State/Country:	JAPAN
Postal Code:	615-8585
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14581460
CORRESPONDENCE DATA	
Fax Number:	(202)408-0924
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	202-371-8976
Email:	firm@rabinberdo.com
Correspondent Name:	RABIN & BERDO, P.C.
Address Line 1:	1101 14TH ST., N.W., SUITE 500
Address Line 4:	WASHINGTON, D.C. 20005
ATTORNEY DOCKET NUMBER:	AI-874
NAME OF SUBMITTER:	ROBERT H. BERDO, JR.
SIGNATURE:	/Robert H. Berdo, Jr./
DATE SIGNED:	03/10/2015
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 2	
source=AI-874-comb_asgn_dec#page1.tif	
source=AI-874-comb_asgn_dec#page2.tif	

ASSIGNMENT OF AND DECLARATION FOR APPLICATION FOR UNITED STATES LETTERS PATENT

WHEREAS Hiroshi TAMAGAWA, Yasuhiro KONDO and Hiroki YAMAMOTO, hereinafter referred to collectively as the assignor and inventor, has invented a certain improvement relating to CHIP PARTS AND METHOD FOR MANUFACTURING THE SAME, CIRCUIT ASSEMBLY HAVING THE CHIP PARTS AND ELECTRONIC DEVICE,

☐ said application being attached hereto;

☒ said application having been filed in the United States Patent and Trademark Office on December 23, 2014 as Application Serial No. 14/581,460 and was amended on _____ (if applicable);

☐ the specification of which was filed under the Patent Cooperation Treaty on _____, Serial No. _____, the United States of America being designated.

AND WHEREAS ROHM CO., LTD. of 21, Saiin Mizosaki-cho, Ukyo-ku, Kyoto-shi, Kyoto 615-8585, Japan, hereinafter referred to as the assignee or applicant, is desirous of acquiring the entire right, title and interest in and to said application, including any and all divisions and continuations thereof, and in and to said invention and any and all patents which may be granted therefor, including any and all renewals, reissues and prolongations thereof;

NOW THIS WITNESSETH, that for and in consideration of One Dollar (\$1.00), and other good and valuable consideration paid by said assignee to said assignor, the receipt of which is hereby acknowledged, said assignor hereby assigns, sells and transfers to said assignee, and said assignee's successors and assigns, the full and exclusive right, title and interest in and to said application, including any and all divisions and continuations thereof, and in and to said invention and any and all patents which may be granted therefor, including any and all renewals, reissues and prolongations thereof; said assignee, and said assignee's successors and assigns, to have, hold, exercise and enjoy the said application, including any and all divisions and continuations thereof, and the said invention and any and all patents which may be granted therefor, including any and all renewals, reissues and prolongations thereof, with all the rights, powers, privileges and advantages in anywise arising from or appertaining thereto, for and during the term or terms of any and all such patents when granted, including any and all renewals, reissues and prolongations thereof, for the use and benefit of said assignee, and said assignee's successors and assigns, in as ample and beneficial a manner as the said assignor might or could have held and enjoyed the same, if this assignment had not been made.

AND said assignor hereby agrees to perform, upon the request of said assignee, or said assignee's successors or assigns, any and all acts relating to the obtaining or to the asserting of said patents, including any and all renewals, reissues and prolongations thereof.

AND said assignor authorizes and requests the Commissioner of Patents and Trademarks to issue Letters Patent on said application, and on any and all divisions and continuations thereof, to said assignee, and said assignee's successors and assigns, in accordance herewith.

As an above-named inventor, I hereby declare that the above-identified application was made or authorized to be made by me, and that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

Address all correspondence and telephone calls to Rabin & Berdo, P.C., 1101 14th Street, N.W., Suite 500, Washington, D.C. 20005, Telephone: (202) 371-8976; Fax: (202) 408-0924, Customer No. 23995.

Continued -Page 2

ASSIGNMENT OF AND DECLARATION FOR APPLICATION FOR UNITED STATES LETTERS PATENT

WITNESS:

Signature: _____

Name: _____

Address: _____

ASSIGNOR (SOLE OR FIRST INVENTOR):

Signature: Hiroshi

Legal Name: Hiroshi TAMAGAWA

Date: Feb. 24, 2015

WITNESS:

Signature: _____

Name: _____

Address: _____

ASSIGNOR (SECOND INVENTOR):

Signature: Yasuhiro Kondo

Legal Name: Yasuhiro KONDO

Date: Feb. 24, 2015

WITNESS:

Signature: _____

Name: _____

Address: _____

ASSIGNOR (THIRD INVENTOR):

Signature: Hiroki Yamamoto

Legal Name: Hiroki YAMAMOTO

Date: Feb. 24, 2015

RABIN & BERDO, P.C., Washington, D.C.